

AUTOMOTIVE

ROHS

GREEN (5-2008)**

Silicon PIN Photodiode



DESCRIPTION

VEMD2500X01 and VEMD2520X01 are high speed and high sensitive PIN photodiodes in a clear epoxy, miniature surface mount package (SMD) with dome lens. The photo sensitive area of the chip is 0.23 mm².

FEATURES

- Package type: surface mount
- · Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- · High radiant sensitivity
- · Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 15^{\circ}$
- Package matched with IR emitter series VSMB2000X01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- · Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC

Note

** Please see document "Vishay Material Category Policy": www.vishay.com/doc?99902

APPLICATIONS

· High speed photo detector

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μA)	φ (deg)	λ _{0.1} (nm)	
VEMD2500X01	12	± 15	350 to 1120	
VEMD2520X01	12	± 15	350 to 1120	

Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VEMD2500X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing	
VEMD2520X01	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing	

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	60	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow solder profile fig. 7	T _{sd}	260	°C
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	250	K/W

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V_{F}		1		V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	32			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		1	10	nA
B'ada a a a a'la a a	V _R = 0 V, f = 1 MHz, E = 0	C _D		4		pF
Diode capacitance	$V_R = 5 \text{ V, f} = 1 \text{ MHz, E} = 0$	C _D		1.3		pF
Open circuit voltage	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	Vo		350		mV
Temperature coefficient of Vo	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{Vo}		- 2.6		mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	I _k		11		μΑ
Temperature coefficient of I _k	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{lk}		0.1		%/K
Reverse light current	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}, \ V_{R} = 5 \text{ V}$	I _{ra}	8.5	12	17	μΑ
Angle of half sensitivity		φ		± 15		deg
Wavelength of peak sensitivity		λ_{p}		900		nm
Range of spectral bandwidth		λ _{0.1}		350 to 1120		nm
Rise time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega,$ $\lambda = 820 \text{ nm}$	t _r		100		ns
Fall time	$V_R = 10 \text{ V}, R_L = 1 \text{ k}\Omega,$ $\lambda = 820 \text{ nm}$	t _f		100		ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

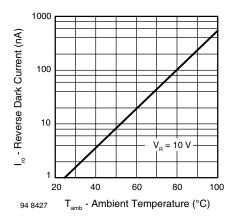


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

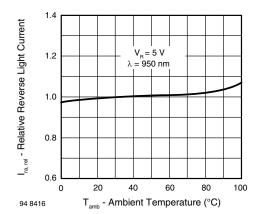


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

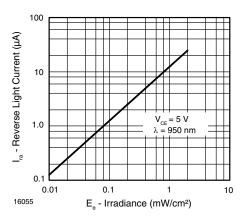


Fig. 3 - Reverse Light Current vs. Irradiance

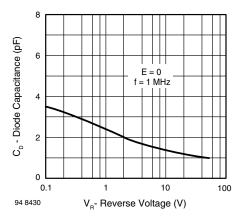


Fig. 4 - Diode Capacitance vs. Reverse Voltage

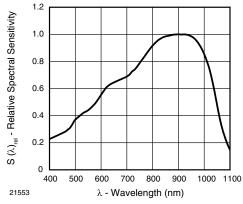


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

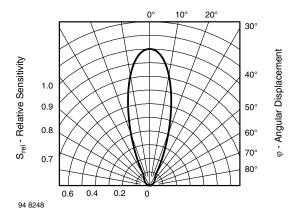


Fig. 6 - Relative Radiant Sensitivity vs. Angular Displacement

REFLOW SOLDER PROFILE

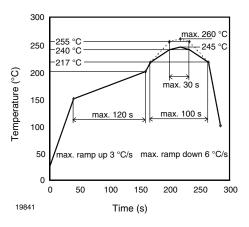


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

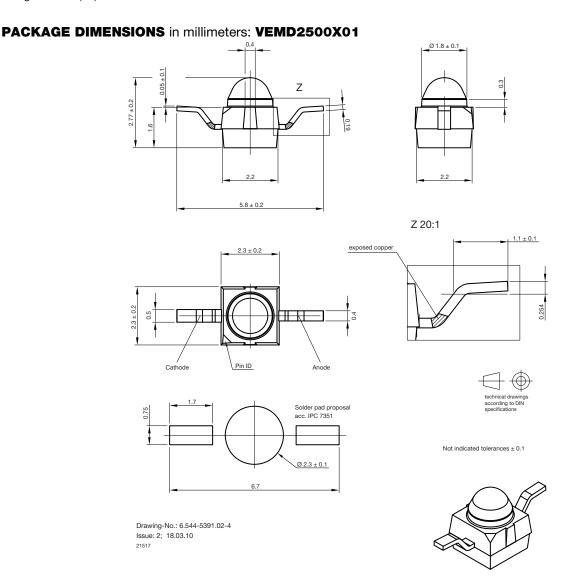
Floor life: 4 weeks

Conditions: T_{amb} < 30 °C, RH < 60 %

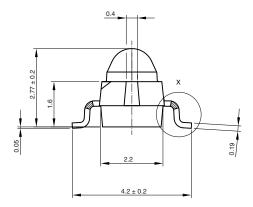
Moisture sensitivity level 2a, acc. to J-STD-020.

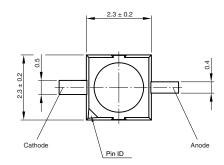
DRYING

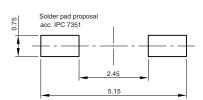
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



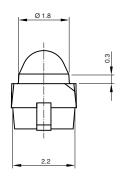
PACKAGE DIMENSIONS in millimeters: VEMD2520X01

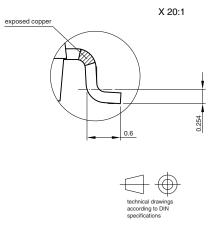




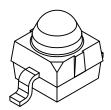


Drawing-No.: 6.544-5383.02-4 Issue: 4; 18.03.10

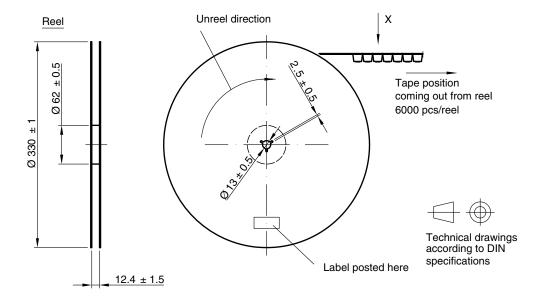




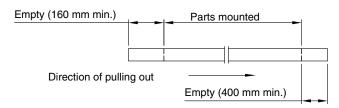
Not indicated tolerances ± 0.1



TAPING AND REEL DIMENSIONS in millimeters: VEMD2500X01

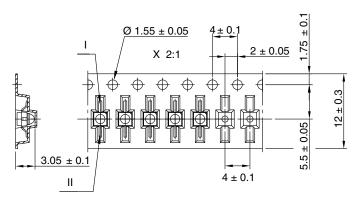


Leader and trailer tape:



Terminal position in tape

Devicce	Lead I	Lead II
VEMT2000		
VEMT2500	Collector	Emitter
VEMD2000		
VEMD2500	Cathode	Anode
VSMB2000	Callioue	Ariode
VSMG2000		
VSMY2850RG	Anode	Cathode

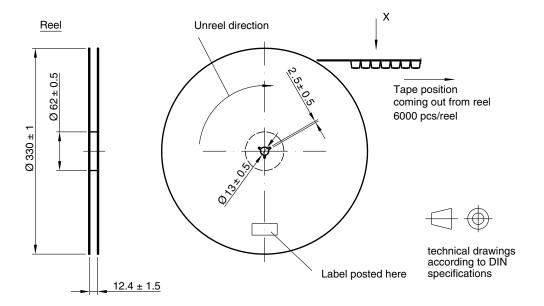


Drawing-No.: 9.800-5100.01-4

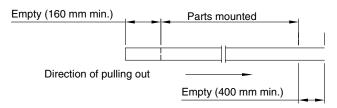
Issue: 2; 18.03.10

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TAPING AND REEL DIMENSIONS in millimeters: VEMD2520X01

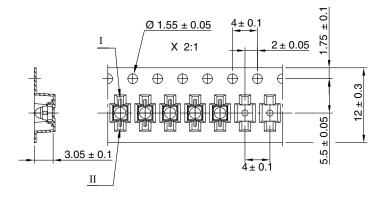


Leader and trailer tape:



Terminal position in tape

Devicce	Lead I	Lead II
VEMT2020		
VEMT2520	Collector	Emitter
VSMB2020		
VSMG2020	0-44-	A I -
VEMD2020	Cathode	Anode
VEMD2520		
VSMY2850G	Anode	Cathode



Drawing-No.: 9.800-5091.01-4

Issue: 3; 18.03.10

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